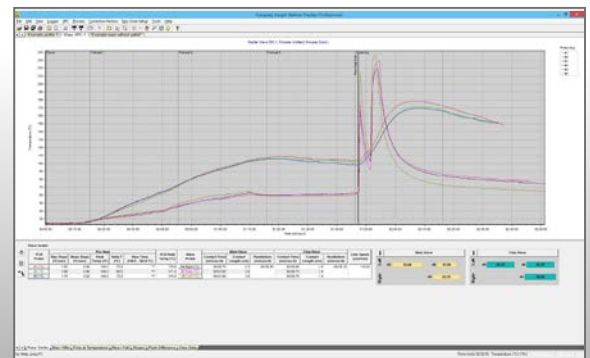
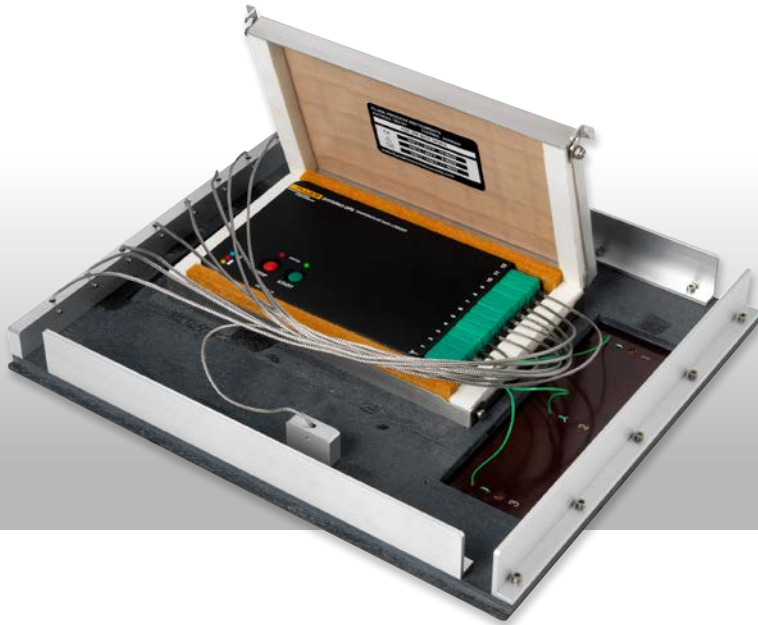


Technical Data

Wave Solder Analysis Kit

for use with a Datapaq® Reflow Tracker® System



Temperature profile with wave pallet

Insight™ software for Reflow Tracker® fully supports the specialized analysis needed to monitor wave soldering. The wave solder analysis kit allows you to adapt your Reflow Tracker temperature profiling system for monitoring the wave soldering process.

Insight software can then be used to analyze data from both the pre-heat and wave soldering phase of the process. Using one software for the complete process ensures compatibility of data throughout the factory and minimizes operator training needs.

You can view all the critical wave process parameters in one easy-to-read table. The wave, chip wave (if present) and pre-heat data will all be shown, together with the temperature profile graph.

The system uses a pallet to carry the data logger and thermal barrier through the process. The pallet incorporates fixed thermocouples ensuring accuracy and repeatability.

System Features

The wave solder analysis kit enables you to profile actual PCB/component temperatures, or alternatively, using the pallet with its integral PCB Coupon the

process stability can be monitored. The results are clearly shown for the pre-heat and wave areas of the process.

Pre-heat analysis includes:

- Maximum slopes
- Rise times
- Maximum temperature in the pre-heat zone
- Delta at the wave
- Maximum temperature over the wave

Wave analysis includes:

- Contact time
- Contact length
- Parallelism
- Line speed

Wizards

Wizards are designed to guide you step-by-step through a particular process, while at each step giving you the opportunity to 'back up' to a previous step if you realize you have made a mistake.

Alarms if the Profile is out of Tolerance

The software can be configured so that if the results are out of limits in the wave or pre-heat areas, an alarm condition is shown.

Wave Solder Analysis Kit



Wave pallet

The wave solder analysis kit is designed for use with Insight Reflow Tracker software. It is compatible with the full range of Datapaq DP5 data loggers, with the exception of the DP5661.

Use Insight™ analysis software to monitor both reflow soldering and wave soldering processes. This reduces the needs for operator training on multiple systems and ensures consistency of data throughout the manufacturing area. The software is fully network compatible, enabling profile data to be shared within the same site.

Part Numbers

- CS5012** **Wave solder pallet** fitted with 9 wave thermocouples and a 3 channel PCB test coupon
- CS5006** **Wave solder pallet** fitted with 3 wave thermocouples and a 3 channel PCB Coupon
Dimensions (H × W × L):
40 mm × 300 mm × 350 mm
(1.5 in × 11.8 in × 13.7 in)
- CS5000A10** **PCB coupon** fitted with 3 Type K thermocouples.
To be used with CS5006 and CS5012.
Enables the Datapaq system to measure the top and bottom pre-heat temperatures in the wave process.
- PA1320/1** **Wave thermocouples**
Thermocouples for use on CS5006 and CS5012 wave solder pallet



Wave pallet

The Fluke Process Instruments Guarantee

Each Fluke Process Instruments system is supported with a full one year warranty. Service contracts available: Complementing the warranty, we offer a yearly service and recalibration contract, which includes free software updates and loan equipment for guaranteed peace of mind.

Fluke Process Instruments

Americas

Everett, WA USA
Tel: +1 425 446 6780
sales@flukeprocessinstruments.com

EMEA

Cambridge, UK
Tel: +44 1223 652 400
sales@flukeprocessinstruments.co.uk

China

Beijing, China
Tel: +86 10 6438 4691
sales@flukeprocessinstruments.com.cn

Asia East and South

India Tel: +91 22 2920 7691
Singapore Tel: +65 6799 5596
sales.asia@flukeprocessinstruments.com

Worldwide Service

Fluke Process Instruments offers services, including repair and calibration. For more information, contact your local office.

www.flukeprocessinstruments.com

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